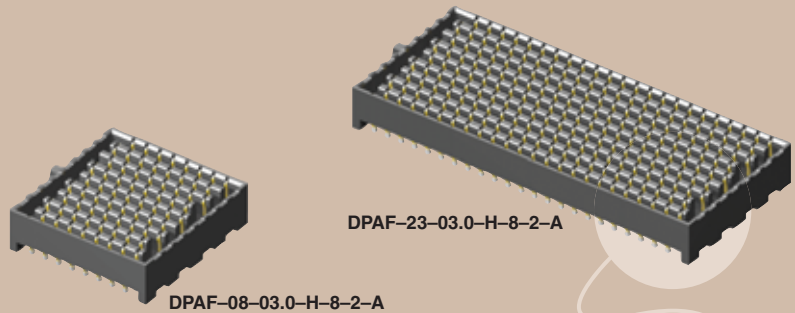




DIFFERENTIAL PAIR ARRAY DPAF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DPAF

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Copper Alloy

Plating:

Au over 50µ" (1,27µm) Ni

Current Rating (2x3):

2.9A @ 30°C Temperature Rise

Operating Temp Range:

-55°C to +125°C

Contact Resistance:

10.4mΩ max

Working Voltage:

300 VAC

Mated Cycles:

100 Cycles

RoHS Compliant:

Yes

Processing:

Max Processing Temp:

230°C for 60 seconds,

or 260°C for 20 seconds 3x

Lead-Free Solderable:

Yes



Mates with:
DPAM



Low Insertion/
Extraction forces

Perimeter
grounds

Staggered
layout
reduces
grounds
required

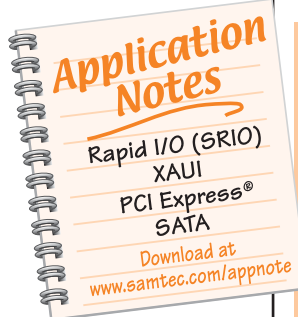
Performance of up to
a terabit per connector

Differential
Pairs

Solder
crimped
to tails

Staggered pitch DPAM/DPAF	Rated @ -3dB Insertion Loss
10mm Stack Height	
Differential Pair Signaling	7.0 GHz / 14.0 Gbps

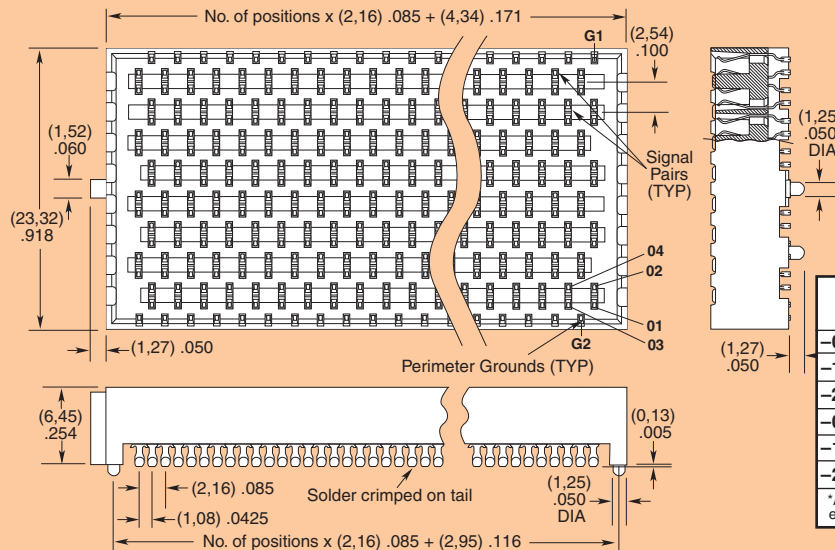
DPAF	PAIRS PER ROW	03.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION
	-08, -15, -23		-H =30µ" (0,76µm) Gold on contact area, Gold Flash on solder tail	-8 =Eight Pair Rows -3 =Three Pair Rows	-2 = Lead-Free Tin Alloy 96.5% Sn/ 3%Ag/ .5% Cu Solder Crimp		-K =(20,00 mm) 0.80" DIA Polyimide film Pick & Place Pad -TR =Tape & Reel



ALSO AVAILABLE

Tin-Lead Solder Charge.
Call Samtec.

Note: Some sizes, styles and options are non-standard, non-returnable.



SIZE	USABLE PAIRS PER ARRAY*
-08 x -8	48 Pairs
-15 x -8	104 Pairs
-23 x -8	168 Pairs
-08 x -3	18 Pairs
-15 x -3	39 Pairs
-23 x -3	63 Pairs

*Assumes first and last pair in each row are grounded

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM